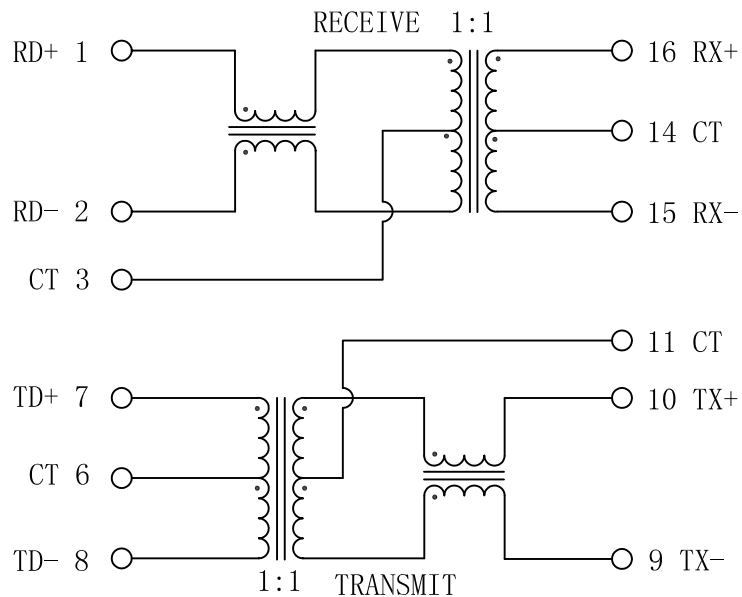


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		01/09/2009	



Electrical Specifications @25°C

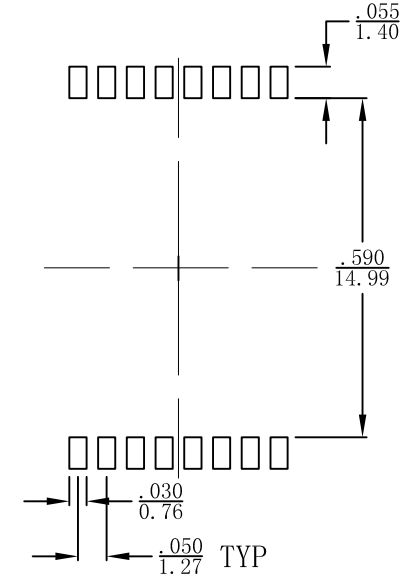
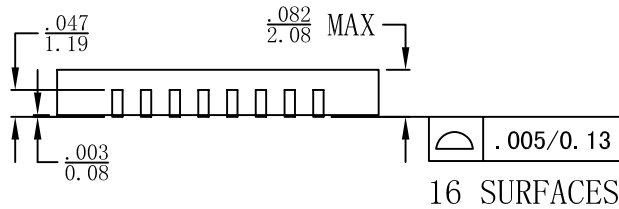
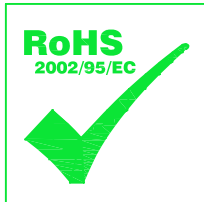
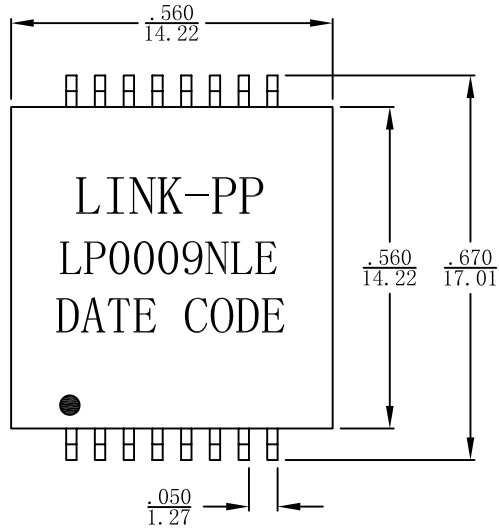
- OCL: 350uH MIN
@100KHz 0.1Vrms
- Turns Ratio ($\pm 5\%$):
TX = 1:1 RX = 1:1
- Insertion Loss (dB MAX):
100KHz-100MHz: -0.9
- Return Loss (dB MIN):
30MHz: -16 60MHz: -12
80MHz: -11
- Differential to Common Mode Rejection (dB MIN):
30MHz: -35 50MHz: -33
100MHz: -20
- Crosstalk (dB MIN):
30MHz: -50 62MHz: -45
100MHz: -40
- Hipot: 1500Vrms MIN
- Operating Temperature: 0°C ~ 70°C.



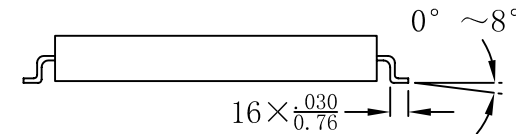
X:X	± 0.20	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.10	CHKD:	TITLE:	
X:XXX	± 0.05	DR: TOM	10/100 PC CARD LAN MAGNETICS MODULES	
ANGLES	$\pm 1^\circ$	UNIT: mm	PART NO.: LP0009NLE	
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP09090115

Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		01/09/2009	



SUGGESTED PAD LAYOUT



NOTES:

1. Peak solder temperature rating per Tabel5-20 in IPC/JEDED J-STD-020C
2. Low profile packages from .094" (2.39mm) to .078" (1.98mm) for PC card and cardbus applications
3. Compliant with IEEE802.3u

X:X	± 0.20	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	± 0.10	CHKD:	TITLE: 10/100 PC CARD LAN MAGNETICS MODULES	
X:XXX	± 0.05	DR: TOM	PART NO. : LP0009NLE	
ANGLES	$\pm 1^\circ$	UNIT: mm		
	SCALE: 2/1	SHEET: 2/2	REV: A	DWG NO. : LP09090115